

## Low IH Series- Pxxx0SxLHL



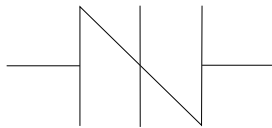
### Agency Approvals

Agency	Agency File Number
	E133083

### Pinout Designation

Not Applicable

### Schematic Symbol



### Description

The low IH series is designed to protect baseband equipment such as modems, line cards, CPE and DSL from damaging overvoltage transients.

The series provides a surface mount solution that enables equipment to comply with global regulatory standards.

### Features and Benefits

- Low voltage overshoot
- Low on-state voltage
- Does not degrade in surge capability after multiple surge events within limit.
- Halogen free and RoHS compliant
- Fails short circuit when surged in excess of ratings
- Low capacitance
- UL Recognized to UL 497B as an Isolated Loop Circuit Protector

### Applicable Global Standards

- TIA-968-A
- TIA-968-B
- ITU K.20/21 Enhanced Level
- ITU K.20/21 Basic Level
- GR 1089 Intra-building
- IEC 61000-4-5 2nd Edition
- YD/T 1082
- YD/T 993
- YD/T 950

### Electrical Characteristics

Part Number	Marking	$V_{DRM}$ @ $I_{DRM} = 5\mu A$	$V_S$ @ 100V/ $\mu s$	$I_H$	$I_S$	$I_T$	$V_T$ @ $I_T = 2.2$ Amps	Capacitance @ 1MHz, 2V bias	
		V min	V max	mA min	mA max	A max	V max	pF min	pF max
P4500SBLHLRP	P45BL	400	570	20*	800	2.2	4	10	50
P4500SCLHLRP	P45L	400	530	50	800	2.2	4	20	50
P3100SDLHLRP	P31DL	275	380	10	800	2.2	4	30	65
P4500SDLHLRP	P45DL	400	570	10	800	2.2	4	25	65

**Notes:**

- Absolute maximum ratings measured at  $T_A = 25^\circ C$  (unless otherwise noted).
- Components are bi-directional.
- \*P4500SBLHLRP  $I_H$  max is 50mA

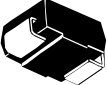
### Surge Ratings

Series	$I_{PP}$								$I_{TSM}$ 50/60 Hz	di/dt
	0.2/310 <sup>1</sup> 0.5/700 <sup>2</sup>	2/10 <sup>1</sup> 2/10 <sup>2</sup>	8/20 <sup>1</sup> 1.2/50 <sup>2</sup>	10/160 <sup>1</sup> 10/160 <sup>2</sup>	5/320 <sup>1</sup> 9/720 <sup>2</sup>	10/360 <sup>1</sup> 10/360 <sup>2</sup>	10/1000 <sup>1</sup> 10/1000 <sup>2</sup>	5/310 <sup>1</sup> 10/700 <sup>2</sup>		
	A min	A min	A min	A min	A min	A min	A min	A min	A min	A/ $\mu s$ max
B	25	250	250	150	100	125	65	100	25	500
C	50	500	400	200	200	175	100	150	35	500
D	-	600	550	-	-	-	130	250	50	500

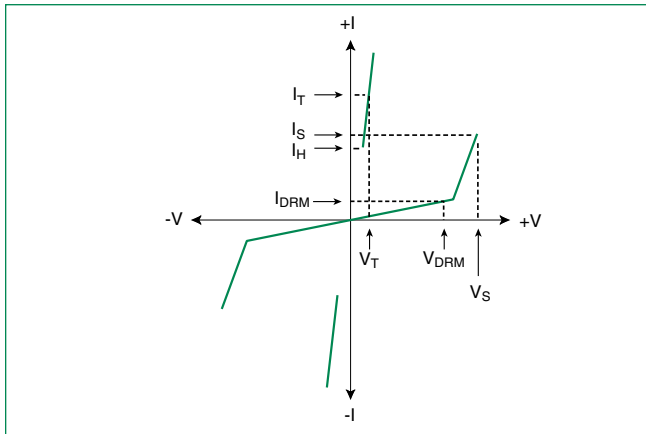
**Notes:**

- 1 Current waveform in  $\mu s$
- 2 Voltage waveform in  $\mu s$
- Peak pulse current rating ( $I_{PP}$ ) is repetitive and guaranteed for the life of the product.
- $I_{PP}$  ratings applicable over temperature range of  $-40^\circ C$  to  $+85^\circ C$
- The component must initially be in thermal equilibrium with  $-40^\circ C \leq T_J \leq +150^\circ C$

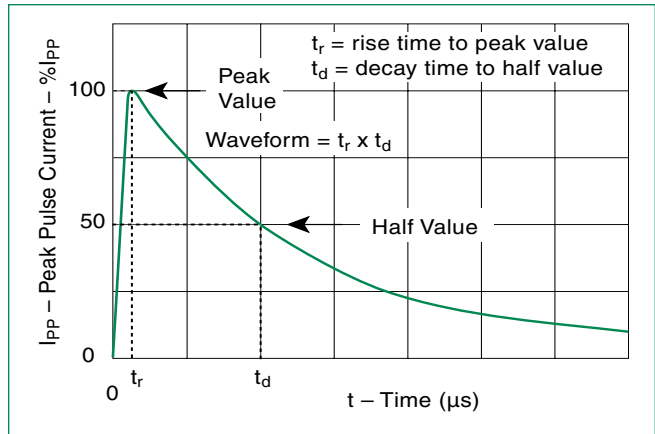
**Thermal Considerations**

Package	Symbol	Parameter	Value	Unit
 DO-214AA	$T_J$	Operating Junction Temperature Range	-40 to +150	°C
	$T_S$	Storage Temperature Range	-65 to +150	°C
	$R_{\theta JA}$	Thermal Resistance: Junction to Ambient	90	°C/W

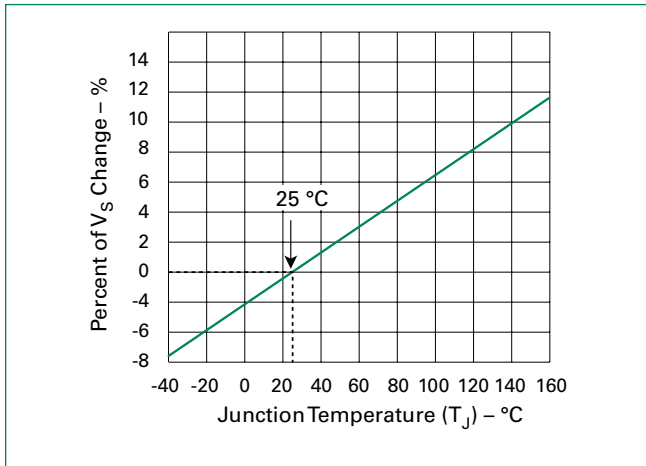
**V-I Characteristics**



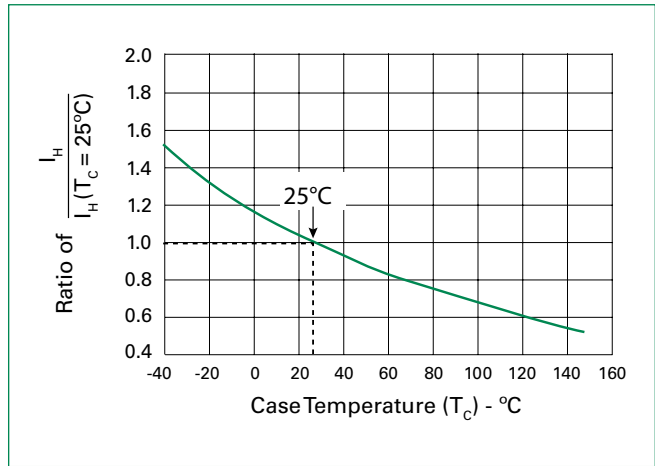
**$t_r \times t_d$  Pulse Waveform**



**Normalized  $V_S$  Change vs. Junction Temperature**

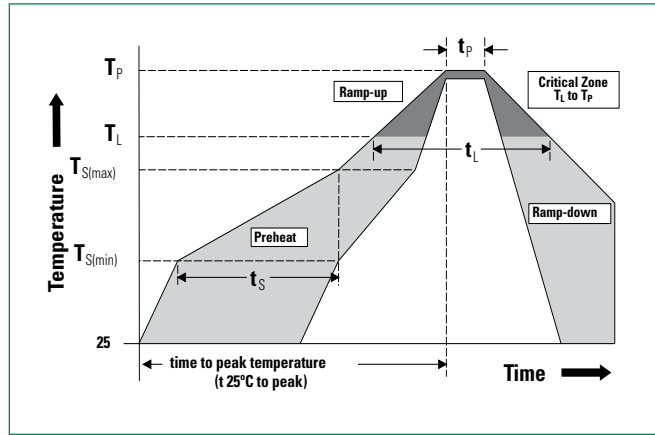


**Normalized DC Holding Current vs. Case Temperature**



**Figure 1. Soldering Parameters**

<b>Reflow Condition</b>		Pb-Free assembly
<b>Pre Heat</b>	- Temperature Min ( $T_{s(min)}$ )	+150°C
	- Temperature Max ( $T_{s(max)}$ )	+200°C
	- Time (Min to Max) ( $t_s$ )	60-180 secs.
<b>Average ramp up rate (Liquidus Temp (<math>T_L</math>) to peak)</b>		3°C/sec. Max.
<b><math>T_{s(max)}</math> to <math>T_L</math> - Ramp-up Rate</b>		3°C/sec. Max.
<b>Reflow</b>	- Temperature ( $T_L$ ) (Liquidus)	+217°C
	- Temperature ( $t_L$ )	60-150 secs.
<b>Peak Temp (<math>T_p</math>)</b>		+260(+0/-5)°C
<b>Time within 5°C of actual Peak Temp (<math>t_p</math>)</b>		30 secs. Max.
<b>Ramp-down Rate</b>		6°C/sec. Max.
<b>Time 25°C to Peak Temp (<math>T_p</math>)</b>		8 min. Max.
<b>Do not exceed</b>		+260°C



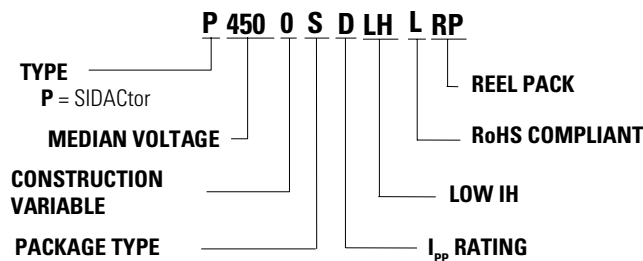
**Physical Specifications**

<b>Lead Material</b>	Copper Alloy
<b>Terminal Finish</b>	100% Matte-Tin Plated
<b>Body Material</b>	UL Recognized compound meeting flammability rating V-0

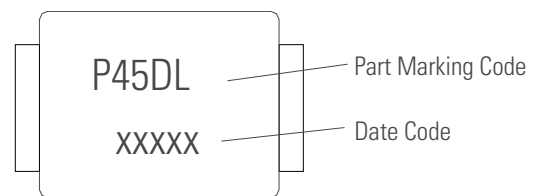
**Environmental Specifications**

<b>High Temp V oltage Blocking</b>	80% Rated $V_{DRM}$ ( $V_{AC}$ Peak) +125°C, 504 or 1008 hrs. MIL-STD-750 (Method 1040) JEDEC, JESD22-A-101
<b>Temp Cycling</b>	-55°C to +150°C, 15 min. dwell, 1000 cycles. MIL-STD-750 (Method 1051) EIA/JEDEC, JESD22-A104
<b>Biased Temp &amp; Humidity</b>	52 $V_{DC}$ (+85°C) 85%RH, 504 up to 1008 hrs. EIA/JEDEC, JESD22-A-101
<b>High Temp Storage</b>	+150°C 1008 hrs. MIL-STD-750 (Method 1031) JEDEC, JESD22-A-101
<b>Low Temp Storage</b>	-65°C, 1008 hrs.
<b>Autoclave (Pressure Cooker Test)</b>	+121°C, 100%RH, 2atm, 96 hrs. EIA/JEDEC, JESD22-A-102
<b>Resistance to Solder Heat</b>	+260°C, 10 secs. MIL-STD-750 (Method 2031)
<b>Moisture Sensitivity Level</b>	85%RH, +85°C, 168 hrs., 3 reflow cycles (+260°C Peak). JEDEC-J-STD-020, Level 1

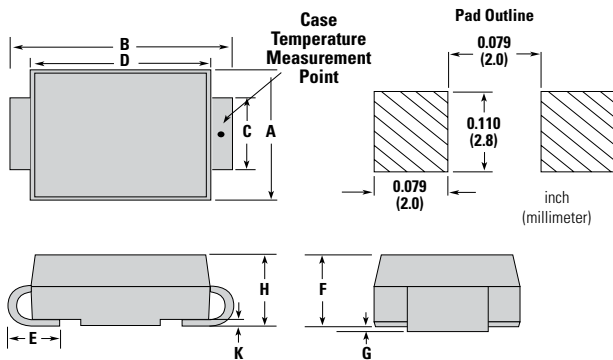
**Part Numbering**



**Part Marking**



**Dimensions — DO-214AA**



Dimensions	Inches		Millimeters	
	Min	Max	Min	Max
A	0.130	0.156	3.30	3.95
B	0.201	0.220	5.10	5.60
C	0.077	0.087	1.95	2.20
D	0.159	0.181	4.05	4.60
E	0.030	0.063	0.75	1.60
F	0.075	0.087	1.90	2.20
G	0.002	0.008	0.05	0.20
H	0.077	0.094	1.95	2.40
K	0.006	0.016	0.15	0.41

**Packing Options**

Package Type	Description	Quantity	Added Suffix	Industry Standard
S	DO-214AA Tape & Reel Pack	2500	RP	EIA-481-D

**Tape and Reel Specification — DO-214AA**

